



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

the application of

SALDANA et al.

Application No. 09/748,708

Filed: December 22, 2000

For: POLISHING APPARATUS AND METHODS
 HAVING HIGH PROCESSING WORKLOAD
 FOR CONTROLLING POLISHING PRESSURE
 APPLIED BY POLISHING HEAD

Atty. Docket No. LAM2P2222A

Examiner: Unassigned

Group Art Unit: 3723

Date: May 2, 2001

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 LEGAL COUNSEL, UNITED STATES PATENT & TRADEMARK OFFICE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on May 2, 2001.

Signed: _____

Neely J. Weldy
 Neely J. Weldy

PRELIMINARY AMENDMENT

Commissioner for Patents
 Washington, D.C. 20231

Sir:

IN THE SPECIFICATION

Please replace the paragraph that begins on page 1, line 9 with the following:

--This Application claims 35 U.S.C. § 120 priority based on, and is a continuation-in-part (CIP) of: (1) co-pending U.S. Patent Application No. 09/644,135, filed August 22, 2000, entitled "SUBAPERTURE CHEMICAL MECHANICAL POLISHING SYSTEM," by Miguel A. Saldana, John M. Boyd, Yehiel Gotkis, and Aleksander A. Owczarz (the First Parent Application); and (2) co-pending U.S. Patent Application No. 09/668,667, filed September 22, 2000, entitled "APPARATUS AND METHODS FOR CONTROLLING RETAINING RING AND WAFER HEAD TILT FOR CHEMICAL MECHANICAL POLISHING," by Damon Vincent Williams (the Second Parent Application), each U.S. Patent Application is hereby incorporated by reference. Additionally, this Application is also related to co-pending U.S. Patent Application No.

09748708-050701

3723

09/493,978, filed January 28, 2000, entitled "SYSTEM METHOD FOR CONTROLLED POLISHING AND PLANARIZATION OF SEMICONDUCTOR WAFERS," by Rod Kistler and Yehiel Gotkis, and such related application is hereby incorporated by reference.--

REMARKS

The Applicants are hereby amending the specification to correct the application number which was provided erroneously as 09/664,135, but should have been 09/644,135.

Respectfully Submitted,
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HAVING HIGH PROCESSING WORKLOAD)	Group Art Unit: 3723
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MARKED UP AMENDMENT

Please replace the paragraph that begins on page 1, line 9 with the following

This Application claims 35 U.S.C. § 120 priority based on, and is a continuation-in-part (CIP) of: (1) co-pending U.S. Patent Application No. [09/664,135] 09/644,135, filed August 22, 2000, entitled "SUBAPERTURE CHEMICAL MECHANICAL POLISHING SYSTEM," by Miguel A. Saldana, John M. Boyd, Yehiel Gotkis, and Aleksander A. Owczarz (the First Parent Application); and (2) co-pending U.S. Patent Application No. 09/668,667, filed September 22, 2000, entitled "APPARATUS AND METHODS FOR CONTROLLING RETAINING RING AND WAFER HEAD TILT FOR CHEMICAL MECHANICAL POLISHING," by Damon Vincent Williams (the Second Parent Application), each U.S. Patent Application is hereby incorporated by reference. Additionally, this Application is also related to co-pending U.S. Patent Application No. 09/493,978, filed January 28, 2000, entitled "SYSTEM METHOD FOR CONTROLLED POLISHING AND PLANARIZATION OF SEMICONDUCTOR WAFERS," by Rod Kistler and Yehiel Gotkis, and such related application is hereby incorporated by reference.--